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Joardar et al.(10) **Pub. No.: US 2024/0237313 A1**(43) **Pub. Date: Jul. 11, 2024**(54) **COOLING SYSTEM FOR POWER
ELECTRONICS****Publication Classification**(51) **Int. Cl.**
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9, 2023.(57) **ABSTRACT**

A cooling system for cooling one or more heat-generating devices includes a heat sink to which the one or more heat-generating devices are thermally coupled and a heat exchanger thermally coupled to the heat sink. The heat exchanger has a first flow path for receiving a primary cooling fluid and a second flow path for receiving a secondary cooling fluid. Heat is transferable to the primary cooling fluid from both the heat sink and the secondary cooling fluid at the heat exchanger.

